



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260331003.2
Qualification of TI Philippines (PHI) as an additional
Assembly & Test site for select package devices
Change Notification / Sample Request

Date: March 31, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260331003.2
Change Notification / Sample Request
Attachments




Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM74700QDBVTQ1	NULL
LM74700QDBVRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260331003.2		PCN Date:	March 31, 2026
Title:	Qualification of TI Philippines (PHI) as an additional Assembly & Test site for select package devices			
Customer Contact:	Change Management team	Dept:	Quality Services	
Proposed 1st Ship Date:	September 27, 2026	Estimated Sample Availability:	May 30, 2026	
*Sample requests received after May 30, 2026 will not be supported.				
Change Type:				
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>
PCN Details				
Description of Change:				
Texas Instruments is pleased to announce the Qualification of TI Philippines (PHI) as an additional Assembly & Test site for select package devices. Material differences between sites as follows.				
	Current Site		Additional Site	
Assembly/Test site	UTAC	CDAT	PHI	
Wire diam/type	1.0mil Au	0.96mil Cu	0.96mil Cu	
Mount compound	SID#PZ0068	4229877	4226215	
Mold compound	SID#CZ0096	4222198	4222198	
Lead finish	NiPdAu	Matte Sn	NiPdAu	
Marking difference	Pin 1 stripe Backside marking Binary marking	Pin 1 dot Binary marking	Pin 1 dot Secondary/Binary marking	
Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.				
Reason for Change:				
Continuity of supply.				
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):				
Review the SDP for full evaluation of the change based on the customer use case.				
Impact on Environmental Ratings:				
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.				
RoHS	REACH	Green Status	IEC 62474	
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	
Changes to product identification resulting from this PCN:				
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City	
UTAC	NS2	THA	Bangpakomg	
TI Chengdu	CDA	CHN	Chengdu	

TI Philippines	PHI	PHL	Baguio City				
Sample product shipping label (not actual product label)							
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:		 G4					
<table border="1"> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table>		MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS	
MSL 2 / 260C / 1 YEAR	SEAL DT						
MSL 1 / 235C / UNLIM	03/29/04						
OPT: ITEM: 39 LBL: 5A (L)T0:1750							
Product Affected:							
LM74700PQDBVRQ1		LM74700QDBVTQ1					
LM74700QDBVRQ1		LM74700VQDBVRQ1					

Qualification Data
Automotive New Product Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
 Approve Date 05-March-2026

Product Attributes

Attributes	Qual Device: LM74700QDBVRQ1	QBS Process Reference: LM74700QDBVRQ1	QBS Package Reference: TMUX4051DYRQ1	QBS Package Reference: TMUX4052DYRQ1	QBS Package Reference: SN6505AQDBVRQ1	QBS Package Reference: LM74700QDDFRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Signal Chain	Signal Chain	Interface	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB	RFAB
Assembly Site	PHI	UTL2	PHI	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	SOT	SOT
Package Designator	DBV	DBV	DYY	DYY	DBV	DDF
Pin Count	6	6	16	16	6	8

QBS: Qual By Similarity, also known as Generic Data

Qual Device LM74700QDBVRQ1 is qualified at MSL2 260C

Note 1: Affected devices in PCN have justification to use Package QBS references for Group A and Group C tests based on AEC-100J Appendix 1 A1.3 assembly site and package attributes were qualified.

Note 2: Affected devices in PCN have justification to use Process QBS references for Group B tests based on AEC-Q100 Rev-J Appendix 1 A1.2, silicon wafer fab and die attributes were qualified.

Note 3: ED/HBM/CDM/LU QBS's LM74700QDDFRQ1 which uses same die in a thinner SOT package.

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: LM74700QDBVRQ1	QBS Process Reference: LM74700QDBVRQ1	QBS Package Reference: TMUX4051DYRQ1	QBS Package Reference: TMUX4052DYRQ1	QBS Package Reference: SN6505AQDBVRQ1	QBS Package Reference: LM74700QDDFRQ1
Test Group A - Accelerated Environment Stress Tests													
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	-	1/77/0	2/154/0	1/77/0	-

PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	Note 1	-	-	-	-	3/231/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	Note 1	-	1/77/0	2/154/0	1/77/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	Note 1	-	-	-	1/77/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	Note 1	-	1/77/0	2/154/0	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	Note 1	-	1/77/0	2/154/0	1/77/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	Note 1	-	1/5/0	2/10/0	1/5/0	3/15/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	Note 1	-	1/45/0	2/90/0	1/45/0	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests													
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	Note 2	3/231/0	-	-	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	Note 2	3/2400/0	-	-	-	-
Test Group C - Package Assembly Integrity Tests													
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	-	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	Note 1	-	-	-	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	Note 1	-	-	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	1	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-	-	-	1/10/0	-
Test Group D - Die Fabrication Reliability Tests													
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDD	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests													
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	Note 3	-	-	-	-	3/9/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	Note 3	-	-	-	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	Note 3	-	-	-	-	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	Note 3	-	-	-	-	1/30/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
TI Qualification ID: R-CHG-2510-037

Qualification Data
Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 SOT at PHI
Approve Date 05-March-2026

Product Attributes

Attributes	QBS Package Reference:	QBS Package Reference:	QBS Package Reference:
	<u>TMUX4051DYYRQ1</u>	<u>TMUX4052DYYRQ1</u>	<u>LM74700QDDFRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB
Assembly Site	PHI	PHI	PHI
Package Group	SOT	SOT	SOT
Package Designator	DYY	DYY	DDF
Pin Count	16	16	8

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	QBS Reference: <u>TMUX4051DYYRQ1</u>	QBS Reference: <u>TMUX4052DYYRQ1</u>	QBS Reference: <u>LM74700QDDFRQ1</u>
Test Group A - Accelerated Environment Stress Tests										
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	1/77/0	2/154/0	-
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	3/231/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	1/22/0	2/44/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	1/22/0	2/44/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	2/154/0	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	1/3/0	2/6/0	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	1/3/0	2/6/0	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	1/3/0	2/6/0	3/9/0

HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	1/70/0	2/140/0	3/210/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST, 2X	Review for delamination	Completed	1/22/0	2/44/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	2/154/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC, 1X	Review for delamination	Completed	1/22/0	2/44/0	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	1/70/0	2/140/0	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	1/22/0	2/44/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	1/3/0	2/6/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	2/90/0	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	1/44/0	2/88/0	3/132/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	1/1/0	2/2/0	3/3/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device LM74700QDBVRQ1 is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2510-037

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-PA-05, SEM-PA-08, SEM-PA-07, SEM-PA-11, SEM-PA-13, SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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